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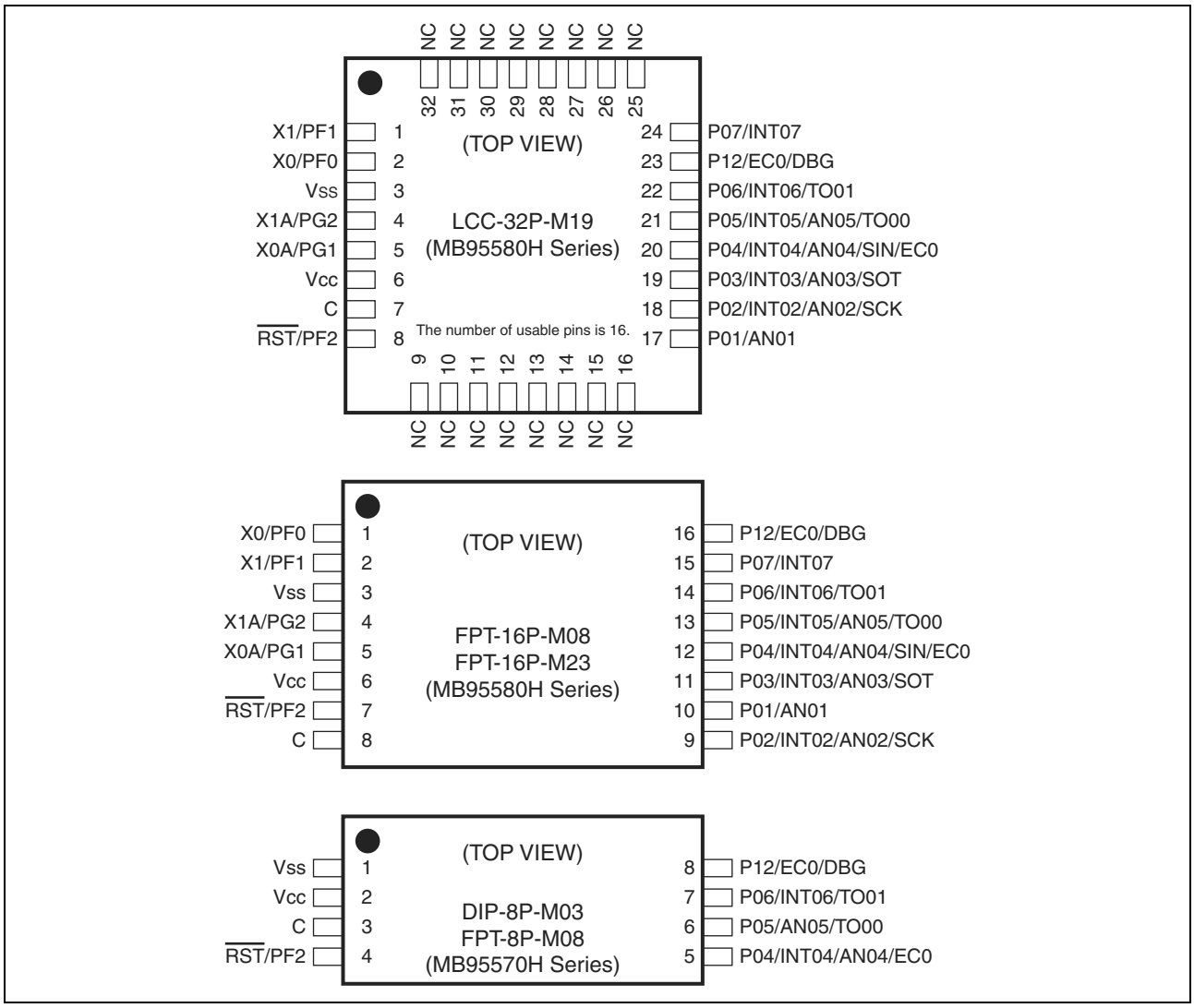
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	F²MC-8FX
Core Size	8-Bit
Speed	16MHz
Connectivity	LINbus, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	13
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	240 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.5V
Data Converters	A/D 5x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-SOIC (0.154", 3.90mm Width)
Supplier Device Package	16-SOP
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb95f582kpf-g-snere2

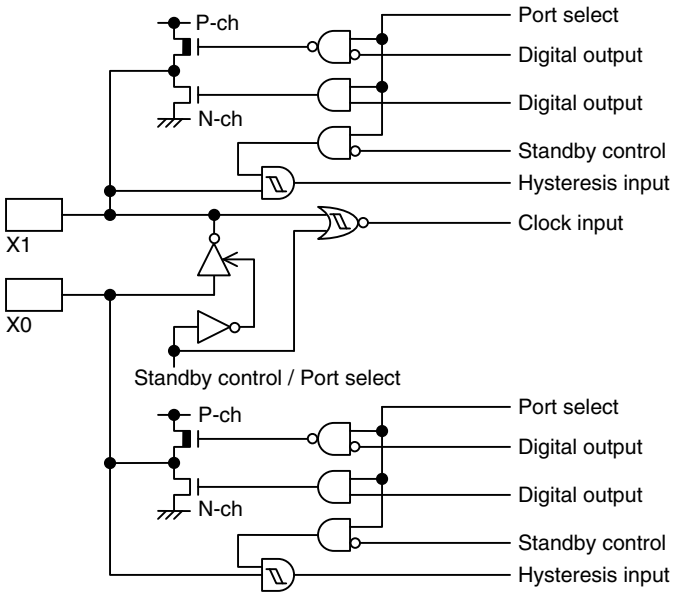
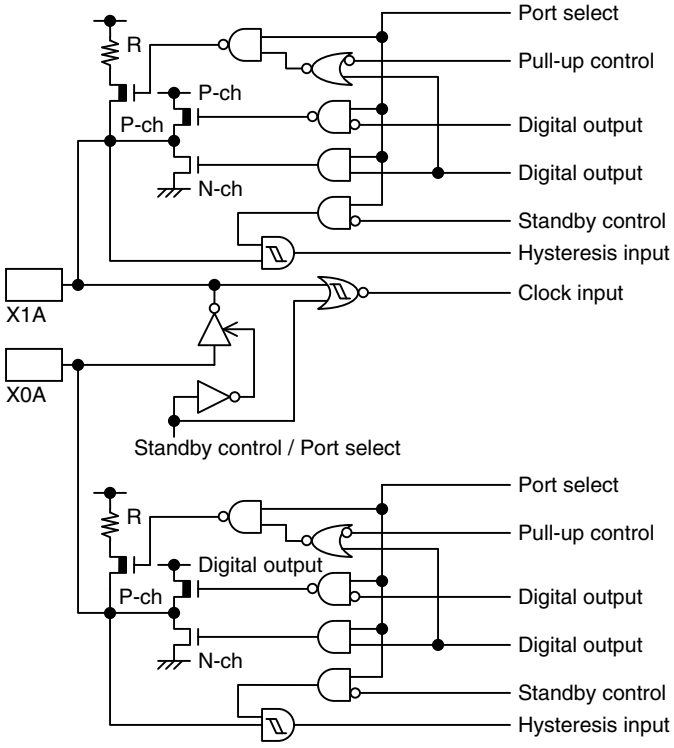
<table>
<tr><th>Part number
Parameter</th><th>MB95F582H</th><th>MB95F583H</th><th>MB95F584H</th><th>MB95F582K</th><th>MB95F583K</th><th>MB95F584K</th></tr>
<tr><td>Time-base timer</td><td colspan="6">Interval time: 0.256 ms to 8.3 s (external clock frequency = 4 MHz)</td></tr>
<tr><td>Hardware/ software watchdog timer</td><td colspan="6">• Reset generation cycle
Main oscillation clock at 10 MHz: 105 ms (Min)
• The sub-CR clock can be used as the source clock of the hardware watchdog timer.</td></tr>
<tr><td>Wild register</td><td colspan="6">It can be used to replace 3 bytes of data.</td></tr>
<tr><td>LIN-UART</td><td colspan="6">• A wide range of communication speed can be selected by a dedicated reload timer.
• It has a full duplex double buffer.
• Both clock synchronous serial data transfer and clock asynchronous serial data transfer are enabled.
• The LIN function can be used as a LIN master or a LIN slave.</td></tr>
<tr><td rowspan="2">8/10-bit A/D converter</td><td colspan="6">5 channels</td></tr>
<tr><td colspan="6">8-bit or 10-bit resolution can be selected.</td></tr>
<tr><td rowspan="2">8/16-bit composite timer</td><td colspan="6">1 channel</td></tr>
<tr><td colspan="6">• The timer can be configured as an "8-bit timer × 2 channels" or a "16-bit timer × 1 channel".
• It has the following functions: interval timer function, PWC function, PWM function and input capture function.
• Count clock: it can be selected from internal clocks (7 types) and external clocks.
• It can output square wave.</td></tr>
<tr><td rowspan="2">External interrupt</td><td colspan="6">6 channels</td></tr>
<tr><td colspan="6">• Interrupt by edge detection (The rising edge, falling edge, or both edges can be selected.)
• It can be used to wake up the device from the standby mode.</td></tr>
<tr><td>On-chip debug</td><td colspan="6">• 1-wire serial control
• It supports serial writing (asynchronous mode).</td></tr>
<tr><td>Watch prescaler</td><td colspan="6">Eight different time intervals can be selected.</td></tr>
<tr><td>Flash memory</td><td colspan="6">• It supports automatic programming (Embedded Algorithm), and program/erase/erase-suspend/erase-resume commands.
• It has a flag indicating the completion of the operation of Embedded Algorithm.
• Flash security feature for protecting the content of the Flash memory
<table>
<tr><td>Number of program/erase cycles</td><td>1000</td><td>10000</td><td>100000</td></tr>
<tr><td>Data retention time</td><td>20 years</td><td>10 years</td><td>5 years</td></tr>
</table></td></tr>
<tr><td>Standby mode</td><td colspan="6">Sleep mode, stop mode, watch mode, time-base timer mode</td></tr>
<tr><td>Package</td><td colspan="6">LCC-32P-M19
FPT-16P-M08
FPT-16P-M23</td></tr>
</table>


NC NC NC NC NC NC NC NC
32 31 30 29 28 27 26 25
X1/PF1 1
X0/PF0 2
Vss 3
X1A/PG2 4
X0A/PG1 5
Vcc 6
C 7
RST/PF2 8
(TOP VIEW)
LCC-32P-M19
(MB95580H Series)
The number of usable pins is 16.
24 P07/INT07
23 P12/EC0/DBG
22 P06/INT06/TO01
21 P05/INT05/AN05/TO00
20 P04/INT04/AN04/SIN/EC0
19 P03/INT03/AN03/SOT
18 P02/INT02/AN02/SCK
17 P01/AN01
9 10 11 12 13 14 15 16
NC NC NC NC NC NC NC NC
X0/PF0 1
X1/PF1 2
Vss 3
X1A/PG2 4
X0A/PG1 5
Vcc 6
RST/PF2 7
C 8
(TOP VIEW)
FPT-16P-M08
FPT-16P-M23
(MB95580H Series)
16 P12/EC0/DBG
15 P07/INT07
14 P06/INT06/TO01
13 P05/INT05/AN05/TO00
12 P04/INT04/AN04/SIN/EC0
11 P03/INT03/AN03/SOT
10 P01/AN01
9 P02/INT02/AN02/SCK
Vss 1
Vcc 2
C 3
RST/PF2 4
(TOP VIEW)
DIP-8P-M03
FPT-8P-M08
(MB95570H Series)
8 P12/EC0/DBG
7 P06/INT06/TO01
6 P05/AN05/TO00
5 P04/INT04/AN04/EC0

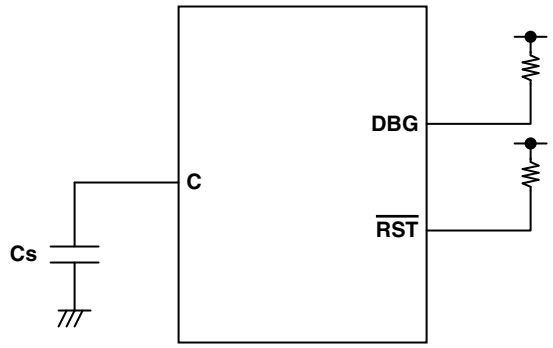
9. Pin Functions (MB95580H Series, 16 pins)

Pin no.	Pin name	I/O circuit type*	Function
1	PF0	B	General-purpose I/O port
	X0		Main clock input oscillation pin
2	PF1	B	General-purpose I/O port
	X1		Main clock I/O oscillation pin
3	V_{SS}	—	Power supply pin (GND)
4	PG2	C	General-purpose I/O port
	X1A		Subclock I/O oscillation pin
5	PG1	C	General-purpose I/O port
	X0A		Subclock input oscillation pin
6	V_{CC}	—	Power supply pin
7	PF2	A	General-purpose I/O port
	$\overline{RST}$		Reset pin Dedicated reset pin on MB95F582H/F583H/F584H
8	C	—	Decoupling capacitor connection pin
9	P02	D	General-purpose I/O port High-current pin
	INT02		External interrupt input pin
	AN02		A/D converter analog input pin
	SCK		LIN-UART clock I/O pin
10	P01	D	General-purpose I/O port High-current pin
	AN01		A/D converter analog input pin
11	P03	D	General-purpose I/O port High-current pin
	INT03		External interrupt input pin
	AN03		A/D converter analog input pin
	SOT		LIN-UART data output pin
12	P04	D	General-purpose I/O port
	INT04		External interrupt input pin
	AN04		A/D converter analog input pin
	SIN		LIN-UART data input pin
	EC0		8/16-bit composite timer ch. 0 clock input pin

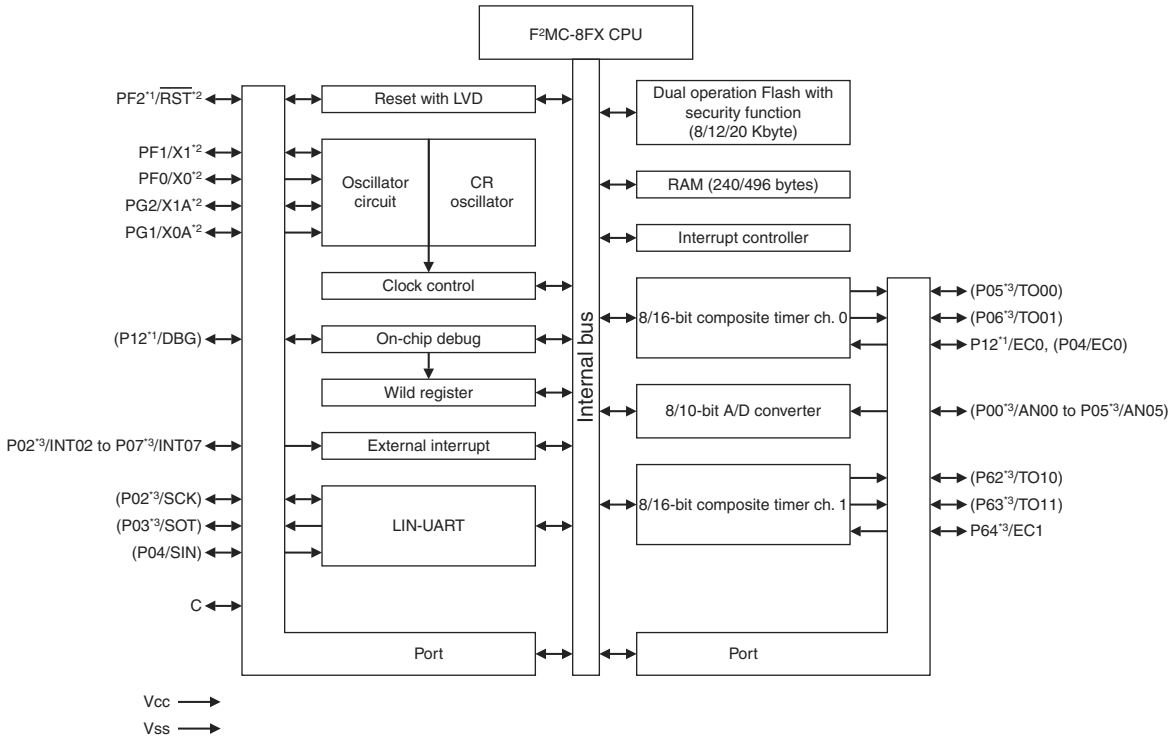
10. I/O Circuit Type

Type	Circuit	Remarks
A		• N-ch open drain output • Hysteresis input • Reset output
B		• Oscillation circuit • High-speed side Feedback resistance: approx. 1 MΩ • CMOS output • Hysteresis input
C		• Oscillation circuit • Low-speed side Feedback resistance: approx.10 MΩ • CMOS output • Hysteresis input • Pull-up control available

- DBG/$\overline{\text{RST}}$/C pins connection diagram



14. Block Diagram (MB95560H Series)



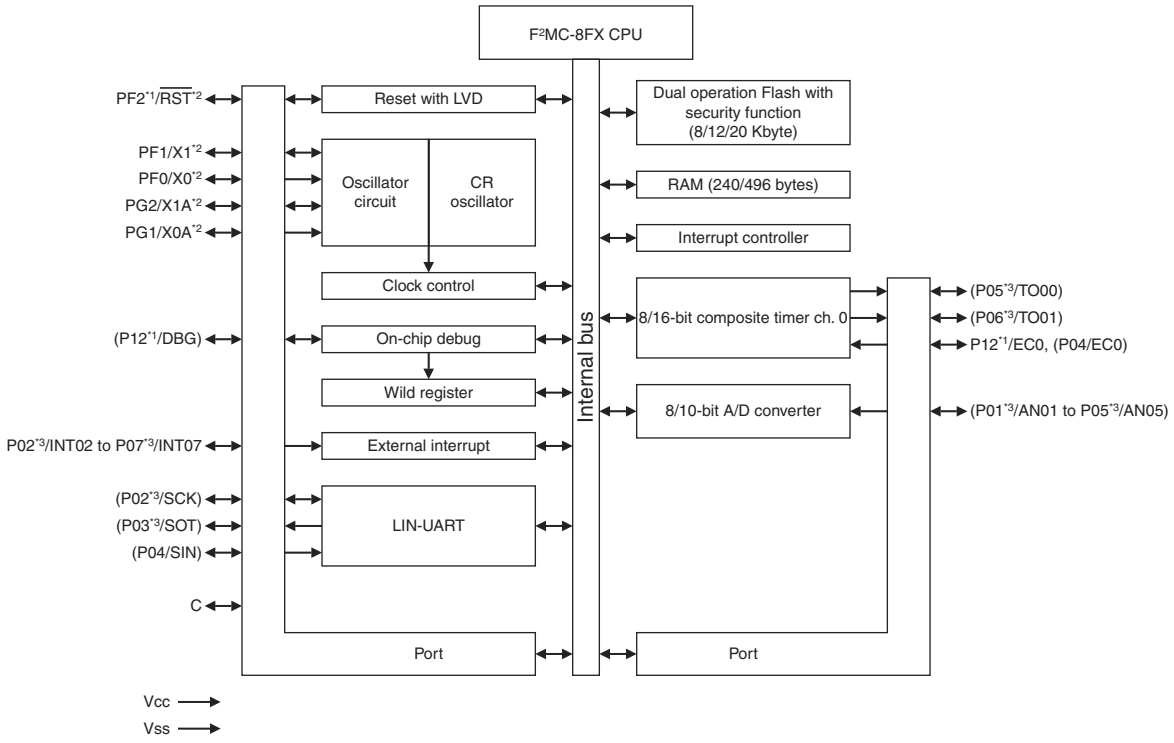
*1: PF2 and P12 are N-ch open drain pins.

*2: Software option

*3: P00 to P03, P05 to P07 and P62 to P64 are high-current pins.

Note: Pins in parentheses indicate that functions of those pins are shared among different resources.

16. Block Diagram (MB95580H Series)



*1: PF2 and P12 are N-ch open drain pins.

*2: Software option

*3: P01 to P03 and P05 to P07 are high-current pins.

Note: Pins in parentheses indicate that functions of those pins are shared among different resources.

19. I/O Map (MB95570H Series)

Address	Register abbreviation	Register name	R/W	Initial value
0000H	PDR0	Port 0 data register	R/W	00000000B
0001H	DDR0	Port 0 direction register	R/W	00000000B
0002H	PDR1	Port 1 data register	R/W	00000000B
0003H	DDR1	Port 1 direction register	R/W	00000000B
0004H	—	(Disabled)	—	—
0005H	WATR	Oscillation stabilization wait time setting register	R/W	11111111B
0006H	PLLC	PLL control register	R/W	000X0000B
0007H	SYCC	System clock control register	R/W	XXX11011B
0008H	STBC	Standby control register	R/W	00000000B
0009H	RSRR	Reset source register	R/W	000XXXXXB
000AH	TBTC	Time-base timer control register	R/W	00000000B
000BH	WPCR	Watch prescaler control register	R/W	00000000B
000CH	WDTC	Watchdog timer control register	R/W	00XX0000B
000DH	SYCC2	System clock control register 2	R/W	XXXX0011B
000EH	STBC2	Standby control register 2	R/W	00000000B
000FH to 0027H	—	(Disabled)	—	—
0028H	PDRF	Port F data register	R/W	00000000B
0029H	DDRF	Port F direction register	R/W	00000000B
002AH, 002BH	—	(Disabled)	—	—
002CH	PUL0	Port 0 pull-up register	R/W	00000000B
002DH to 0035H	—	(Disabled)	—	—
0036H	T01CR1	8/16-bit composite timer 01 status control register 1	R/W	00000000B
0037H	T00CR1	8/16-bit composite timer 00 status control register 1	R/W	00000000B
0038H to 0049H	—	(Disabled)	—	—
004AH	EIC20	External interrupt circuit control register ch. 4/ch. 5	R/W	00000000B
004BH	EIC30	External interrupt circuit control register ch. 6/ch. 7	R/W	00000000B
004CH, 004DH	—	(Disabled)	—	—
004EH	LVDR	LVDR reset voltage selection ID register	R/W	00000000B
004FH to 006BH	—	(Disabled)	—	—

Address	Register abbreviation	Register name	R/W	Initial value
006C$_H$	ADC1	8/10-bit A/D converter control register 1	R/W	00000000$_B$
006D$_H$	ADC2	8/10-bit A/D converter control register 2	R/W	00000000$_B$
006E$_H$	ADDH	8/10-bit A/D converter data register (upper)	R/W	00000000$_B$
006F$_H$	ADDL	8/10-bit A/D converter data register (lower)	R/W	00000000$_B$
0070$_H$	—	(Disabled)	—	—
0071$_H$	FSR2	Flash memory status register 2	R/W	00000000$_B$
0072$_H$	FSR	Flash memory status register	R/W	000X0000$_B$
0073$_H$	SWRE0	Flash memory sector write control register 0	R/W	00000000$_B$
0074$_H$	FSR3	Flash memory status register 3	R	000XXXXX$_B$
0075$_H$	FSR4	Flash memory status register 4	R/W	00000000$_B$
0076$_H$	WREN	Wild register address compare enable register	R/W	00000000$_B$
0077$_H$	WROR	Wild register data test setting register	R/W	00000000$_B$
0078$_H$	—	Mirror of register bank pointer (RP) and direct bank pointer (DP)	—	—
0079$_H$	ILR0	Interrupt level setting register 0	R/W	11111111$_B$
007A$_H$	ILR1	Interrupt level setting register 1	R/W	11111111$_B$
007B$_H$, 007C$_H$	—	(Disabled)	—	—
007D$_H$	ILR4	Interrupt level setting register 4	R/W	11111111$_B$
007E$_H$	ILR5	Interrupt level setting register 5	R/W	11111111$_B$
007F$_H$	—	(Disabled)	—	—
0F80$_H$	WRARH0	Wild register address setting register (upper) ch. 0	R/W	00000000$_B$
0F81$_H$	WRARL0	Wild register address setting register (lower) ch. 0	R/W	00000000$_B$
0F82$_H$	WRDR0	Wild register data setting register ch. 0	R/W	00000000$_B$
0F83$_H$	WRARH1	Wild register address setting register (upper) ch. 1	R/W	00000000$_B$
0F84$_H$	WRARL1	Wild register address setting register (lower) ch. 1	R/W	00000000$_B$
0F85$_H$	WRDR1	Wild register data setting register ch. 1	R/W	00000000$_B$
0F86$_H$	WRARH2	Wild register address setting register (upper) ch. 2	R/W	00000000$_B$
0F87$_H$	WRARL2	Wild register address setting register (lower) ch. 2	R/W	00000000$_B$
0F88$_H$	WRDR2	Wild register data setting register ch. 2	R/W	00000000$_B$
0F89$_H$ to 0F91$_H$	—	(Disabled)	—	—
0F92$_H$	T01CR0	8/16-bit composite timer 01 status control register 0	R/W	00000000$_B$
0F93$_H$	T00CR0	8/16-bit composite timer 00 status control register 0	R/W	00000000$_B$
0F94$_H$	T01DR	8/16-bit composite timer 01 data register	R/W	00000000$_B$
0F95$_H$	T00DR	8/16-bit composite timer 00 data register	R/W	00000000$_B$
0F96$_H$	TMCR0	8/16-bit composite timer 00/01 timer mode control register	R/W	00000000$_B$
0F97$_H$ to 0FC2$_H$	—	(Disabled)	—	—

21. Interrupt Source Table (MB95560H Series)

Interrupt source	Interrupt request number	Vector table address		Bit name of interrupt level setting register	Priority order of interrupt sources of the same level (occurring simultaneously)
		Upper	Lower		
External interrupt ch. 4	IRQ00	FFFA$_H$	FFFB$_H$	L00 [1:0]	High
External interrupt ch. 5	IRQ01	FFF8$_H$	FFF9$_H$	L01 [1:0]	
External interrupt ch. 2	IRQ02	FFF6$_H$	FFF7$_H$	L02 [1:0]	
External interrupt ch. 6					
External interrupt ch. 3	IRQ03	FFF4$_H$	FFF5$_H$	L03 [1:0]	
External interrupt ch. 7					
—	IRQ04	FFF2$_H$	FFF3$_H$	L04 [1:0]	
8/16-bit composite timer ch. 0 (lower)	IRQ05	FFF0$_H$	FFF1$_H$	L05 [1:0]	
8/16-bit composite timer ch. 0 (upper)	IRQ06	FFEE$_H$	FFEF$_H$	L06 [1:0]	
LIN-UART (reception)	IRQ07	FFEC$_H$	FFED$_H$	L07 [1:0]	
LIN-UART (transmission)	IRQ08	FFEA$_H$	FFEB$_H$	L08 [1:0]	
—	IRQ09	FFE8$_H$	FFE9$_H$	L09 [1:0]	
—	IRQ10	FFE6$_H$	FFE7$_H$	L10 [1:0]	
—	IRQ11	FFE4$_H$	FFE5$_H$	L11 [1:0]	
—	IRQ12	FFE2$_H$	FFE3$_H$	L12 [1:0]	
—	IRQ13	FFE0$_H$	FFE1$_H$	L13 [1:0]	
8/16-bit composite timer ch. 1 (upper)	IRQ14	FFDE$_H$	FFDF$_H$	L14 [1:0]	
—	IRQ15	FFDC$_H$	FFDD$_H$	L15 [1:0]	
—	IRQ16	FFDA$_H$	FFDB$_H$	L16 [1:0]	
—	IRQ17	FFD8$_H$	FFD9$_H$	L17 [1:0]	
8/10-bit A/D converter	IRQ18	FFD6$_H$	FFD7$_H$	L18 [1:0]	
Time-base timer	IRQ19	FFD4$_H$	FFD5$_H$	L19 [1:0]	
Watch prescaler	IRQ20	FFD2$_H$	FFD3$_H$	L20 [1:0]	
—	IRQ21	FFD0$_H$	FFD1$_H$	L21 [1:0]	
8/16-bit composite timer ch. 1 (lower)	IRQ22	FFCE$_H$	FFCF$_H$	L22 [1:0]	
Flash memory	IRQ23	FFCC$_H$	FFCD$_H$	L23 [1:0]	Low

24.2 Recommended Operating Conditions

(V_{SS} = 0.0 V)

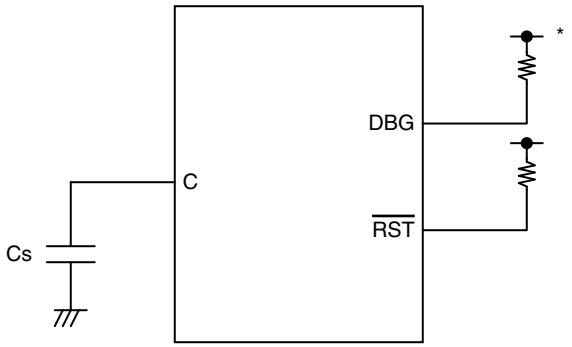
Parameter	Symbol	Value		Unit	Remarks	
		Min	Max			
Power supply voltage	V_{CC}	2.4*1, *2	5.5*1	V	In normal operation	Other than on-chip debug mode
		2.3	5.5		Hold condition in stop mode	
		2.9	5.5		In normal operation	On-chip debug mode
		2.3	5.5		Hold condition in stop mode	
Decoupling capacitor	C_S	0.022	1	µF	*3	
Operating temperature	T_A	−40	+85	°C	Other than on-chip debug mode	
		+5	+35		On-chip debug mode	

*1: The value varies depending on the operating frequency, the machine clock and the analog guaranteed range.

*2: The minimum power supply voltage becomes 2.88 V when a product with the low-voltage detection reset is used.

*3: Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The decoupling capacitor for the V_{CC} pin must have a capacitance equal to or larger than the capacitance of C_S. For the connection to a decoupling capacitor C_S, see the diagram below. To prevent the device from unintentionally entering an unknown mode due to noise, minimize the distance between the C pin and C_S and the distance between C_S and the V_{SS} pin when designing the layout of a printed circuit board.

• DBG / $\overline{\text{RST}}$ / C pins connection diagram



*: Connect the DBG pin to an external pull-up resistor of 2 kΩ or above. After power-on, ensure that the DBG pin does not stay at “L” level until the reset output is released. The DBG pin becomes a communication pin in debug mode. Since the actual pull-up resistance depends on the tool used and the interconnection length, refer to the tool document when selecting a pull-up resistor.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated under these conditions.

Any use of semiconductor devices will be under their recommended operating condition.
Operation under any conditions other than these conditions may adversely affect reliability of device and could result in device failure.

No warranty is made with respect to any use, operating conditions or combinations not represented on this data sheet. If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.

(V_{CC} = 5.0 V ± 10%, V_{SS} = 0.0 V, T_A = –40 °C to +85 °C)

Parameter	Symbol	Pin name	Condition	Value			Unit	Remarks
				Min	Typ*1	Max*2		
Power supply current*5	I_{LVD}	V_{CC}	Current consumption for the low-voltage detection circuit	—	3.6	6.6	µA	
	I_{CRH}		Current consumption for the main CR oscillator	—	220	280	µA	
	I_{CRL}		Current consumption for the sub-CR oscillator oscillating at 100 kHz	—	5.1	9.3	µA	
	I_{NSTBY}		Current consumption difference between normal standby mode and deep standby mode T_A = +25 °C	—	20	30	µA	

*1: V_{CC} = 5.0 V, T_A = + 25 °C

*2: V_{CC} = 5.5 V, T_A = + 85 °C (unless otherwise specified)

*3: P00, P62, P63 and P64 are only available on MB95F562H/F562K/F563H/F563K/F564H/F564K.

*4: P01, P02, P03, P07, PF0, PF1, PG1 and PG2 are only available on MB95F562H/F562K/F563H/F563K/F564H/F564K/F582H/F582K/F583H/F583K/F584H/F584K.

*5:
- The power supply current is determined by the external clock. When the low-voltage detection option is selected, the power-supply current will be the sum of adding the current consumption of the low-voltage detection circuit (I_{LVD}) to one of the value from I_{CC} to I_{CCH}. In addition, when both the low-voltage detection option and the CR oscillator are selected, the power supply current will be the sum of adding up the current consumption of the low-voltage detection circuit, the current consumption of the CR oscillators (I_{CRH}, I_{CRL}) and a specified value. In on-chip debug mode, the CR oscillator (I_{CRH}) and the low-voltage detection circuit are always enabled, and current consumption therefore increases accordingly.
- See “24.4 AC Characteristics: Clock Timing” for F_{CH} and F_{CL}.
- See “24.4 AC Characteristics: Source Clock / Machine Clock” for F_{MP} and F_{MPL}.

*6: In sub-CR clock mode, the power supply current value is the sum of adding I_{CRL} to I_{CCLS} or I_{CCT}. In addition, when the sub-CR clock mode is selected with F_{MPL} being 50 kHz, the current consumption increases accordingly.

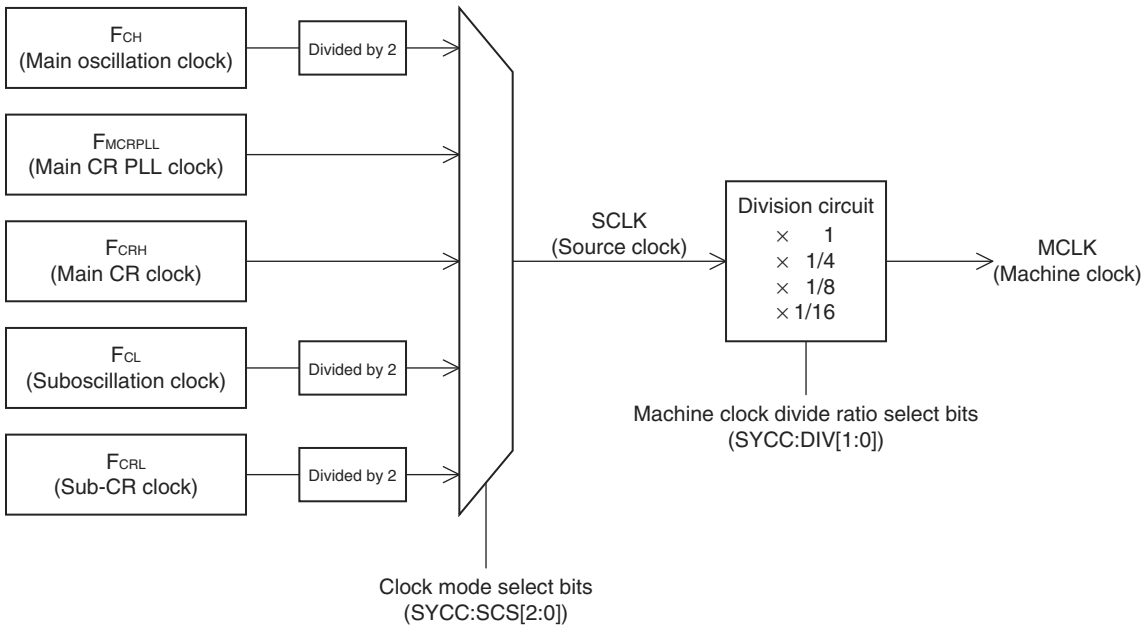
24.4 AC Characteristics

24.4.1 Clock Timing

(V_{CC} = 2.4 V to 5.5 V, V_{SS} = 0.0 V, T_A = –40 °C to +85 °C)

Parameter	Symbol	Pin name	Condition	Value			Unit	Remarks
				Min	Typ	Max		
Clock frequency	F_{CH}	X0, X1	—	1	—	16.25	MHz	When the main oscillation circuit is used
		X0	X1: open	1	—	12	MHz	When the main external clock is used
		X0, X1	*	1	—	32.5	MHz	
	F_{CRH}	—	—	3.92	4	4.08	MHz	Operating conditions • The main CR clock is used. • 0 °C ≤ T_A ≤ +70 °C
				3.8	4	4.2	MHz	Operating conditions • The main CR clock is used. • –40 °C ≤ T_A < 0 °C, +70 °C < T_A ≤ +85 °C
	F_{MCRPLL}	—	—	7.84	8	8.16	MHz	Operating conditions • PLL multiplication rate: 2 • 0 °C ≤ T_A ≤ +70 °C
				7.6	8	8.4	MHz	Operating conditions • PLL multiplication rate: 2 • –40 °C ≤ T_A < 0 °C, +70 °C < T_A ≤ +85 °C
				9.8	10	10.2	MHz	Operating conditions • PLL multiplication rate: 2.5 • 0 °C ≤ T_A ≤ +70 °C
				9.5	10	10.5	MHz	Operating conditions • PLL multiplication rate: 2.5 • –40 °C ≤ T_A < 0 °C, +70 °C < T_A ≤ +85 °C
				11.76	12	12.24	MHz	Operating conditions • PLL multiplication rate: 3 • 0 °C ≤ T_A ≤ +70 °C
				11.4	12	12.6	MHz	Operating conditions • PLL multiplication rate: 3 • –40 °C ≤ T_A < 0 °C, +70 °C < T_A ≤ +85 °C
				15.68	16	16.32	MHz	Operating conditions • PLL multiplication rate: 4 • 0 °C ≤ T_A ≤ +70 °C
				15.2	16	16.8	MHz	Operating conditions • PLL multiplication rate: 4 • –40 °C ≤ T_A < 0 °C, +70 °C < T_A ≤ +85 °C
	F_{CL}	X0A, X1A	—	—	32.768	—	kHz	When the suboscillation circuit is used
				—	32.768	—	kHz	When the sub-external clock is used
	F_{CRL}	—	—	50	100	150	kHz	When the sub-CR clock is used

• Schematic diagram of the clock generation block

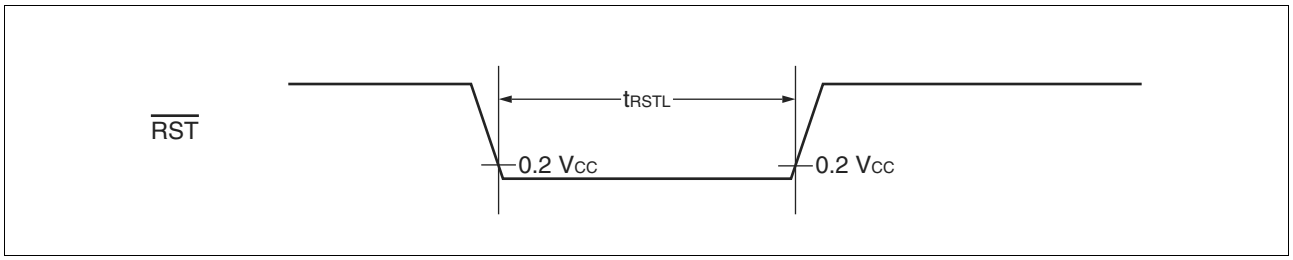


24.4.3 External Reset

(V_{CC} = 5.0 V ± 10%, V_{SS} = 0.0 V, T_A = –40 °C to +85 °C)

Parameter	Symbol	Value		Unit	Remarks
		Min	Max		
$\overline{RST}$ "L" level pulse width	t_{RSTL}	2 t_{MCLK}*1	—	ns	In normal operation

*1: See "Source Clock / Machine Clock" for t_{MCLK}.



Sampling is executed at the rising edge of the sampling clock*1, and serial clock delay is enabled*2. (ESCR register: SCES bit = 0, ECCR register: SCDE bit = 1)

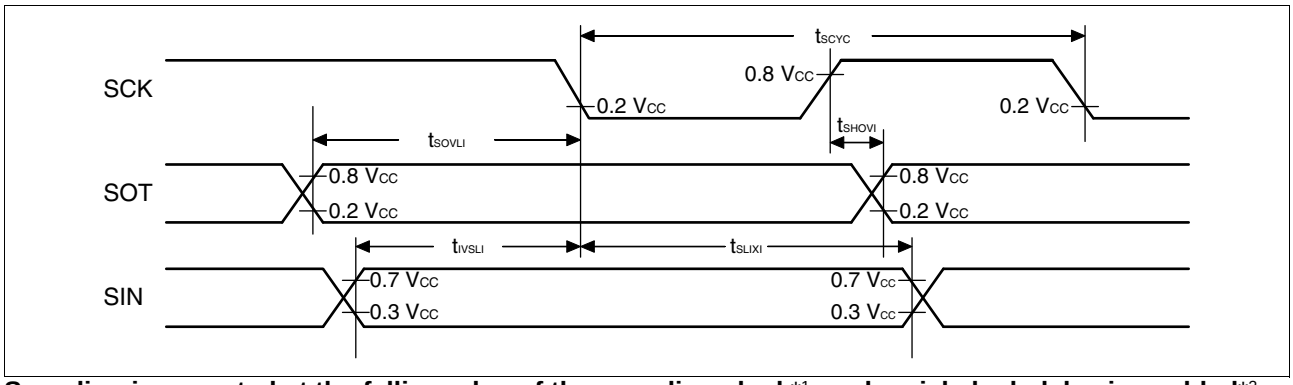
(V_{CC} = 5.0 V ± 10%, V_{SS} = 0.0 V, T_A = –40 °C to +85 °C)

Parameter	Symbol	Pin name	Condition	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK	Internal clock operation output pin: C_L = 80 pF + 1 TTL	5 t_{MCLK}*3	—	ns
SCK ↑→ SOT delay time	t_{SHOVI}	SCK, SOT		–50	+50	ns
Valid SIN → SCK ↓	t_{IVSLI}	SCK, SIN		t_{MCLK}*3 + 80	—	ns
SCK ↓→ valid SIN hold time	t_{SLIXI}	SCK, SIN		0	—	ns
SOT → SCK ↓ delay time	t_{SOVLI}	SCK, SOT		3 t_{MCLK}*3 – 70	—	ns

*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function that delays the output signal of the serial clock for half clock.

*3: See “Source Clock / Machine Clock” for t_{MCLK}.



Sampling is executed at the falling edge of the sampling clock*1, and serial clock delay is enabled*2. (ESCR register: SCES bit = 1, ECCR register: SCDE bit = 1)

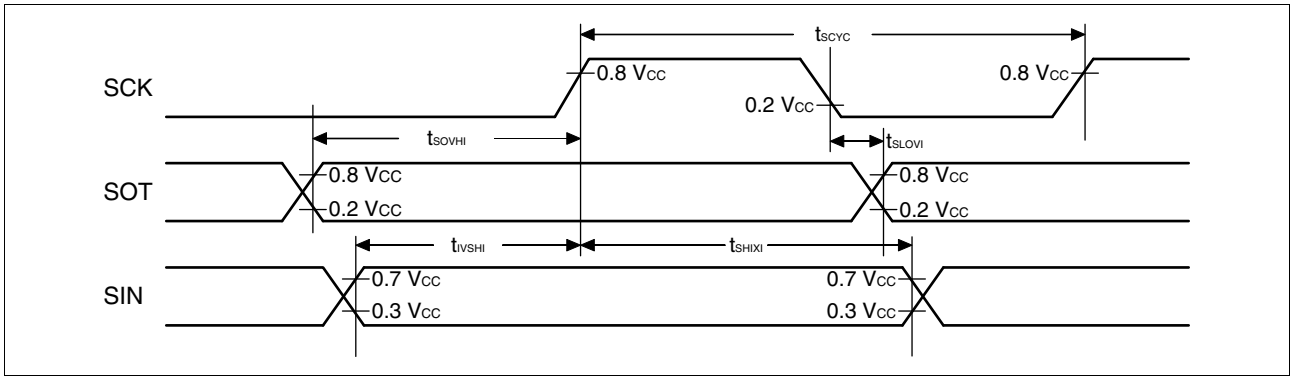
(V_{CC} = 5.0 V ± 10%, V_{SS} = 0.0 V, T_A = –40 °C to +85 °C)

Parameter	Symbol	Pin name	Condition	Value		Unit
				Min	Max	
Serial clock cycle time	t_{SCYC}	SCK	Internal clock operating output pin: C_L = 80 pF + 1 TTL	5 t_{MCLK}*3	—	ns
SCK ↓→ SOT delay time	t_{SLOVI}	SCK, SOT		–50	+50	ns
Valid SIN → SCK ↑	t_{IVSHI}	SCK, SIN		t_{MCLK}*3 + 80	—	ns
SCK ↑→ valid SIN hold time	t_{SHIXI}	SCK, SIN		0	—	ns
SOT → SCK ↑ delay time	t_{SOVHI}	SCK, SOT		3 t_{MCLK}*3 – 70	—	ns

*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function that delays the output signal of the serial clock for half clock.

*3: See “Source Clock / Machine Clock” for t_{MCLK}.



24.4.7 Low-voltage Detection

(V_{SS} = 0.0 V, T_A = –40 °C to +85 °C)

Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
Release voltage*	V_{DL+}	2.52	2.7	2.88	V	At power supply rise
		2.61	2.8	2.99		
		2.89	3.1	3.31		
		3.08	3.3	3.52		
Detection voltage*	$V_{DL–}$	2.43	2.6	2.77	V	At power supply fall
		2.52	2.7	2.88		
		2.80	3	3.20		
		2.99	3.2	3.41		
Hysteresis width	V_{HYS}	—	100	—	mV	
Power supply start voltage	V_{off}	—	—	2.3	V	
Power supply end voltage	V_{on}	4.9	—	—	V	
Power supply voltage change time (at power supply rise)	t_r	650	—	—	µs	Slope of power supply that the reset release signal generates within the rating (V_{DL+})
Power supply voltage change time (at power supply fall)	t_f	650	—	—	µs	Slope of power supply that the reset detection signal generates within the rating (V_{DL-})
Reset release delay time	t_{d1}	—	—	30	µs	
Reset detection delay time	t_{d2}	—	—	30	µs	
LVD threshold voltage transition stabilization time	t_{stb}	10	—	—	µs	

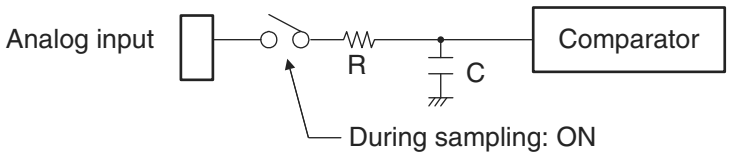
*: The release voltage and the detection voltage can be selected by using the LVD reset voltage selection ID register (LVDR) in the low-voltage detection reset circuit. For details of the LVDR register, refer to “CHAPTER 18 LOW-VOLTAGE DETECTION RESET CIRCUIT” in “New 8FX MB95560H/570H/580H Series Hardware Manual”.

24.5.2 Notes on Using A/D Converter

- External impedance of analog input and its sampling time

  The A/D converter of the MB95560H/570H/580H Series has a sample and hold circuit. If the external impedance is too high to keep sufficient sampling time, the analog voltage charged to the capacitor of the internal sample and hold circuit is insufficient, adversely affecting A/D conversion precision. Therefore, to satisfy the A/D conversion precision standard, considering the relationship between the external impedance and minimum sampling time, either adjust the register value and operating frequency or decrease the external impedance so that the sampling time is longer than the minimum value. In addition, if sufficient sampling time cannot be secured, connect a capacitor of about 0.1 µF to the analog input pin.

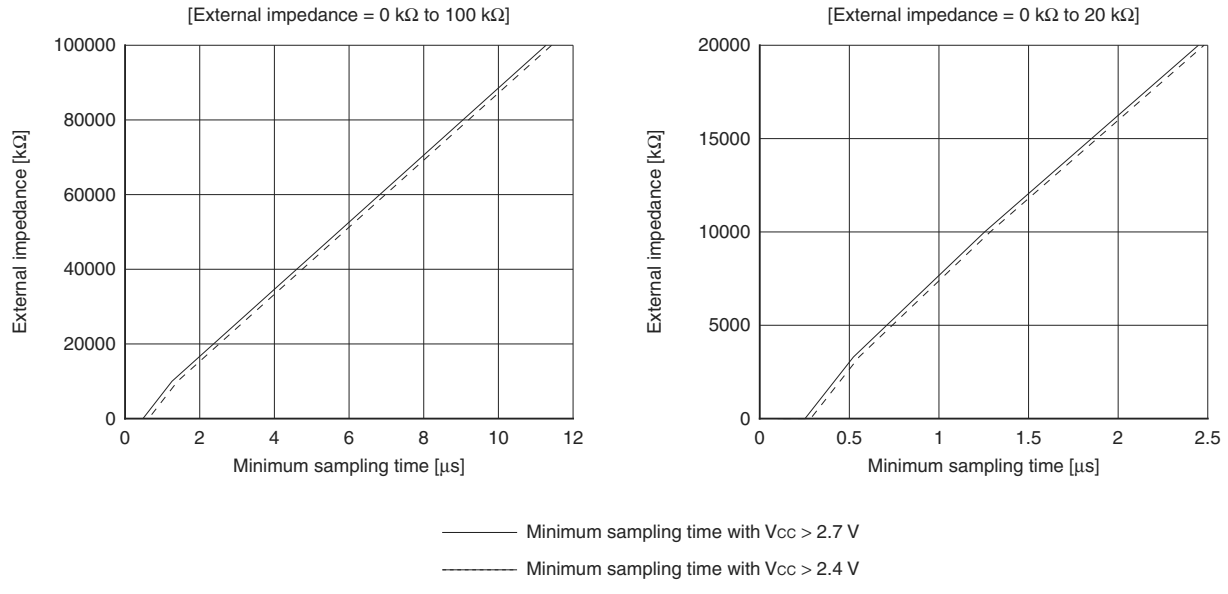
- Analog input equivalent circuit



V_{CC}	R	C
4.5 V ≤ V_{CC} ≤ 5.5 V	1.45 kΩ (Max)	14.89 pF (Max)
2.7 V ≤ V_{CC} < 4.5 V	2.7 kΩ (Max)	14.89 pF (Max)

Note: The values are reference values.

- Relationship between external impedance and minimum sampling time

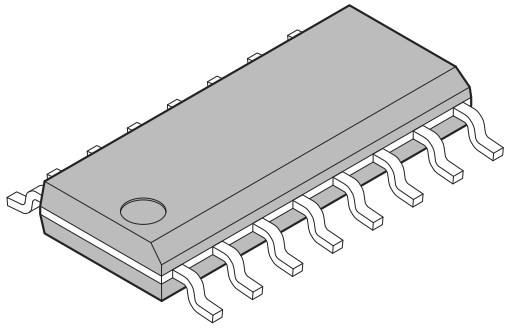


- A/D conversion error

  As |V_{CC} – V_{SS}| decreases, the A/D conversion error increases proportionately.

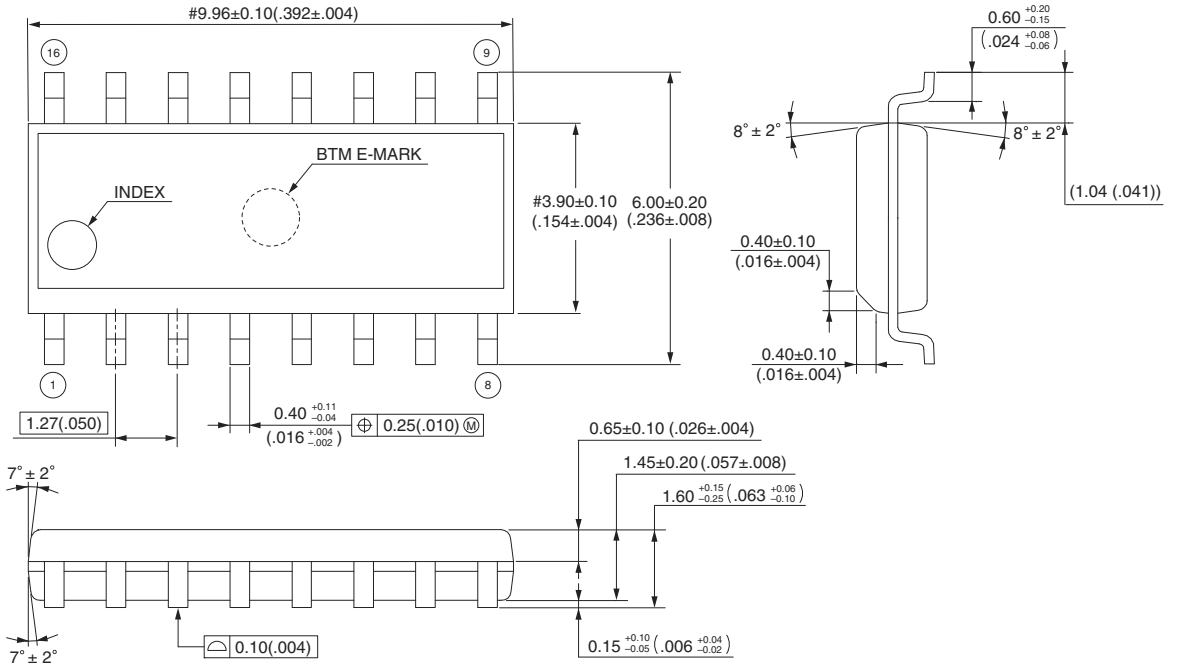
27. Ordering Information

Part number	Package
MB95F562HWQN-G-SNE1 MB95F562HWQN-G-SNERE1 MB95F562KWQN-G-SNE1 MB95F562KWQN-G-SNERE1 MB95F563HWQN-G-SNE1 MB95F563HWQN-G-SNERE1 MB95F563KWQN-G-SNE1 MB95F563KWQN-G-SNERE1 MB95F564HWQN-G-SNE1 MB95F564HWQN-G-SNERE1 MB95F564KWQN-G-SNE1 MB95F564KWQN-G-SNERE1	32-pin plastic QFN (LCC-32P-M19)
MB95F562HPF-G-SNE2 MB95F562KPF-G-SNE2 MB95F563HPF-G-SNE2 MB95F563KPF-G-SNE2 MB95F564HPF-G-SNE2 MB95F564KPF-G-SNE2 MB95F564KPF-G-UNE2	20-pin plastic SOP (FPT-20P-M09)
MB95F562HPFT-G-SNE2 MB95F562KPFT-G-SNE2 MB95F563HPFT-G-SNE2 MB95F563KPFT-G-SNE2 MB95F564HPFT-G-SNE2 MB95F564KPFT-G-SNE2 MB95F564KPFT-G-UNE2	20-pin plastic TSSOP (FPT-20P-M10)
MB95F582HWQN-G-SNE1 MB95F582HWQN-G-SNERE1 MB95F582KWQN-G-SNE1 MB95F582KWQN-G-SNERE1 MB95F583HWQN-G-SNE1 MB95F583HWQN-G-SNERE1 MB95F583KWQN-G-SNE1 MB95F583KWQN-G-SNERE1 MB95F584HWQN-G-SNE1 MB95F584HWQN-G-SNERE1 MB95F584KWQN-G-SNE1 MB95F584KWQN-G-SNERE1	32-pin plastic QFN (LCC-32P-M19)
MB95F582HPFT-G-SNE2 MB95F582KPFT-G-SNE2 MB95F583HPFT-G-SNE2 MB95F583KPFT-G-SNE2 MB95F584HPFT-G-SNE2 MB95F584KPFT-G-SNE2	16-pin plastic TSSOP (FPT-16P-M08)

16-pin plastic SOP		
 (FPT-16P-M23)	Lead pitch	1.27 mm
	Package width × package length	3.90 mm × 9.96 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.75 mm MAX
	Weight	0.12 g

16-pin plastic SOP
(FPT-16P-M23)

Note 1) Pins width and pins thickness include plating thickness.
Note 2) Pins width do not include tie bar cutting remainder.
Note 3) #: These dimensions do not include resin protrusion.



Dimensions in mm (inches).
Note: The values in parentheses are reference values.

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